

ABSTRACT

A liquid epoxy resin composition is provided
5 comprising (A) a liquid epoxy resin, (B) an optional curing
agent, (C) a curing accelerator, (D) an inorganic filler,
and (E) acrylic submicron particles of core-shell structure
formed of polymers or copolymers comprising an alkyl
acrylate and/or alkyl methacrylate as a monomeric component,
10 the core having a Tg of up to -10°C , the shell having a Tg
of $80-150^{\circ}\text{C}$. The composition is adherent to surfaces of
silicon chips, especially polyimide resins and nitride film
and useful as sealant for flip chip type semiconductor
devices.